Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L19	2	"4510446".pn.	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 11:24
L20	2	"5369491".pn.	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 11:24
L21	2	"5377404".pn.	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 11:25
L22	2	"6232559".pn.	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 11:28
L23	0	testing near pcb and opening near spacings	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 11:29
L24	45	testing near pcb and spacings	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 11:34
L25	0	john near Durkot.inv.	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 11:34
L26	0	john near Durkot .inv.	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 11:34
L27	0	Durkot near john .inv.	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 11:35
L28	0	pcb adj opening near spacings and testing	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 11:35
L29	3	pcb and opening near spacings and testing	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 12:40
L30	2	kuo-chi near chiu.inv.	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 12:45

L31	3369234	magnetic adj component and substrate and circuit and second circuit	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 13:06
L32	15	magnetic adj component and substrate and circuit and second adj circuit	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 14:59
L33	0	GMR adj component and substrate and circuit and second adj circuit	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 13:30
L34	20	GMR and substrate and circuit and second adj circuit	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 13:18
L35	282	substrate and circuit near layer and insulating and second adj circuit	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 13:31
L36	0	substrate and circuit near layer and insulating and second adj circuit and multi near pole	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 13:32
L37	1	substrate and circuit near layer and multi near pole near magnetic	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 13:32
L38	1	substrate and circuit near layer and multipole near magnetic	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 13:32
L39	15	substrate and circuit near layer and multi and pole near magnetic	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 13:36
L40	8	("5525941").URPN.	USPAT	OR	ON	2005/08/10 13:33
L41	273	multi adj pole near magnetic	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 13:48
L42	0	multi adj pole near magnetic and pcb and tin near filled	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 13:36
L43	0	multi adj pole near magnetic and pcb and tin	USPAT; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 13:36